

MA2SP02

Silicon epitaxial planar type

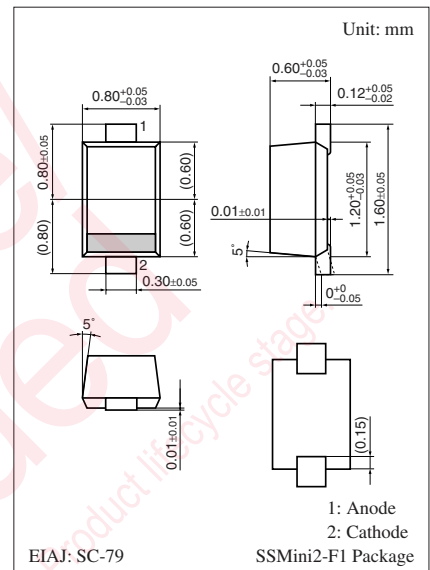
For high frequency switch

■ Features

- Small terminal capacitance C_t
- Small forward dynamic resistance r_f
- Miniature package and surface mounting type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	100	mA
Power dissipation	P_D	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

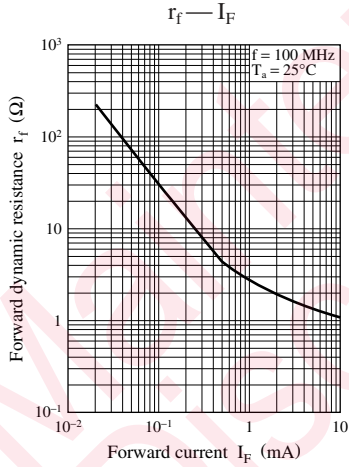
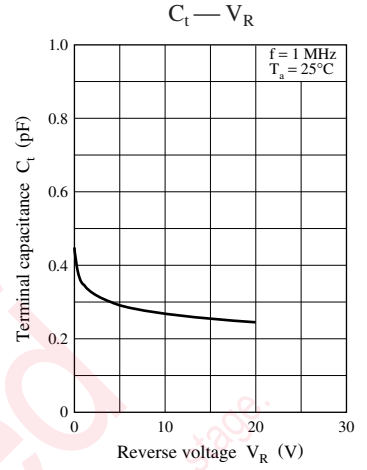
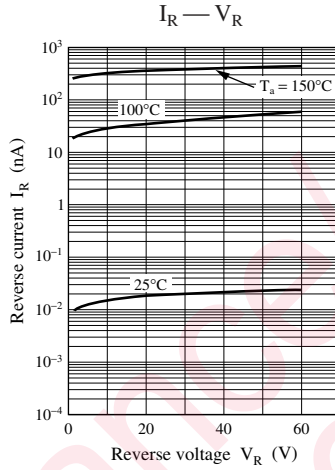
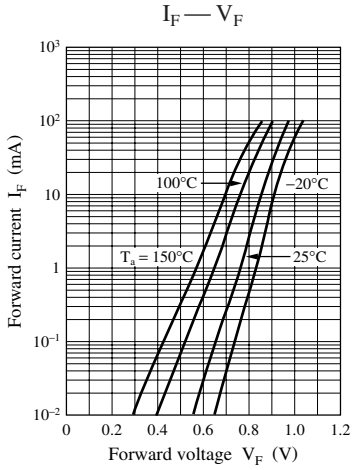


Marking Symbol: 3P

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10 \text{ mA}$			1.0	V
Reverse current	I_R	$V_R = 60 \text{ V}$			100	nA
Terminal capacitance	C_t	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$			0.5	pF
Forward dynamic resistance	r_f	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$			2.0	Ω

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



Maintenance/Discontinued includes following four Product lifecycle stage:
planned maintenance type
maintenance type
planned discontinued type
discontinued type
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